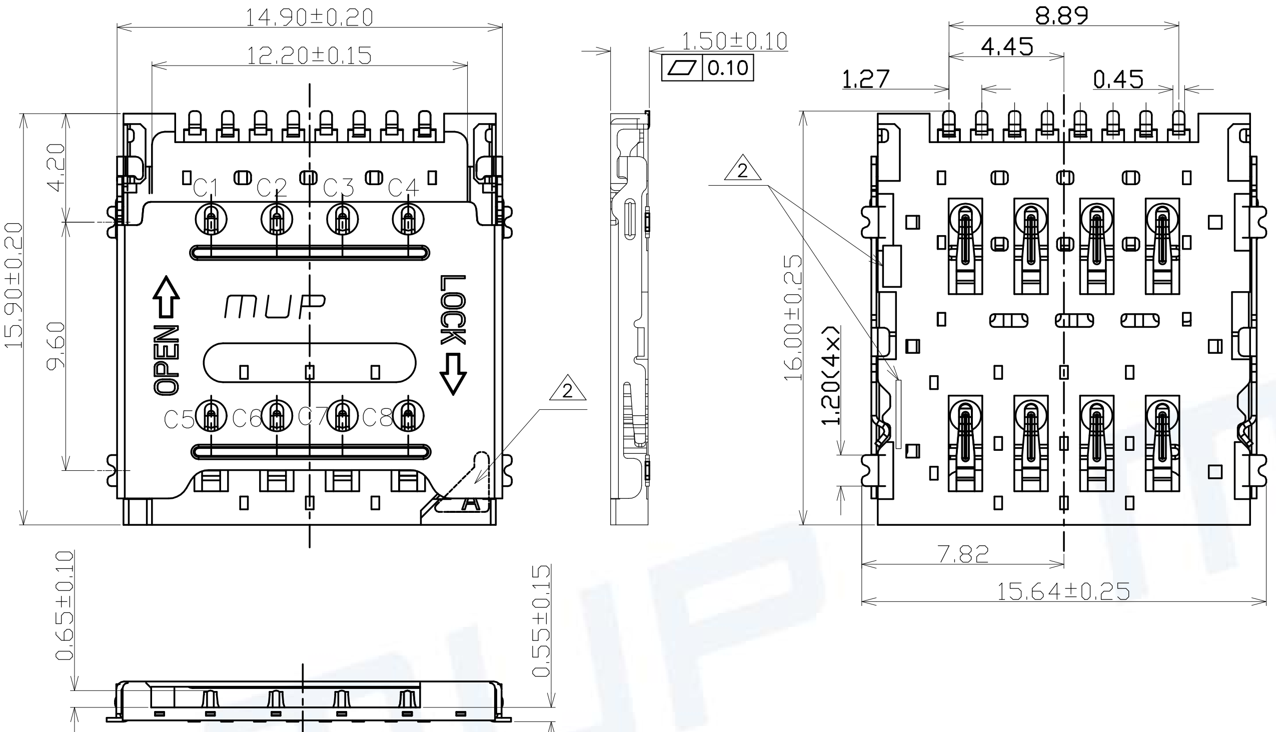
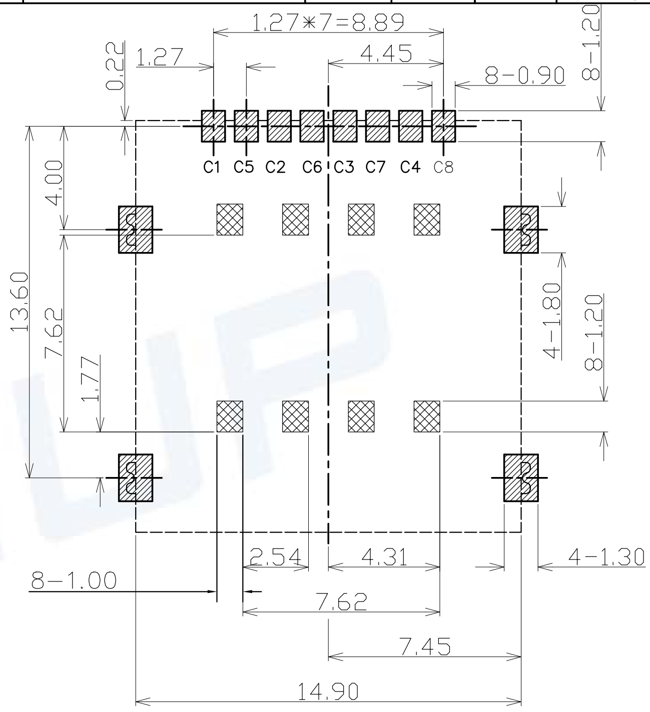
REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
1	NEW REVISION			Henry	2015/03/13
2	Plastic change			Henry	2022/08/11
3	Original Model C791-4			Henry	2023/10/19





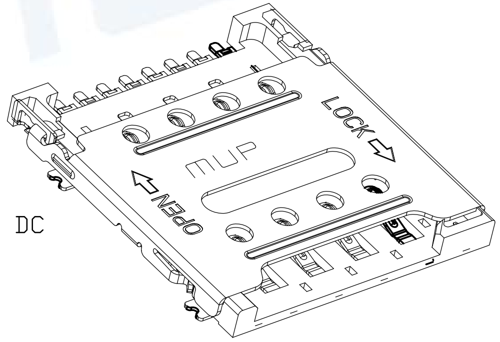
RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

▨ PAD AREA

⬚ CONNECTOR OUTLINE

▩ NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS
1.General Characteristics
Dimensions:15.90LX14.90WX1.50H mm
Weight:Approx 0.53±0.2g
Durability:5,000 cycles min.
2.Electrical Characteristics
Contact resisitance:50mΩ typical, 100mΩMax
Insulation resistance:>1000M/500V DC
3.Solderability
Vaporphase:215°C, 30sec.Max
IR reflow:250°C,5sec.Max
Manual soldering:370°C.3sec.Max
4.Environmental Characteristics
Operating temperature:-40°C~+85°C
Operating humidity:10%~+75%RH
*5.Note:
It's easy to cause short-circuit between the shell and the fillet weld leg at the power is on when lift the cover greater than 135 degree .
Suggestion:
Do not lift the cover when the current is switched on.



Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **Micro-SIM Card Connector**
MODEL NO: **MUP-C7091-04**
TYPE : **H1.50mm 8 PIN(Long shell &New Body)**

PROJ.	UNIT	SCALE
⊕	mm	1:1

RoHS PROCESS COMPLIANT

CUSTOMER DRAWING

DRAWN	Henry Mar.13.2015	DWG NO.:	DWG-C7091-04-01
CHECKED	Henry Mar.13.2015	SHEET	REVISION
APPROVAL	Simon Mar.13.2015	1/1	3